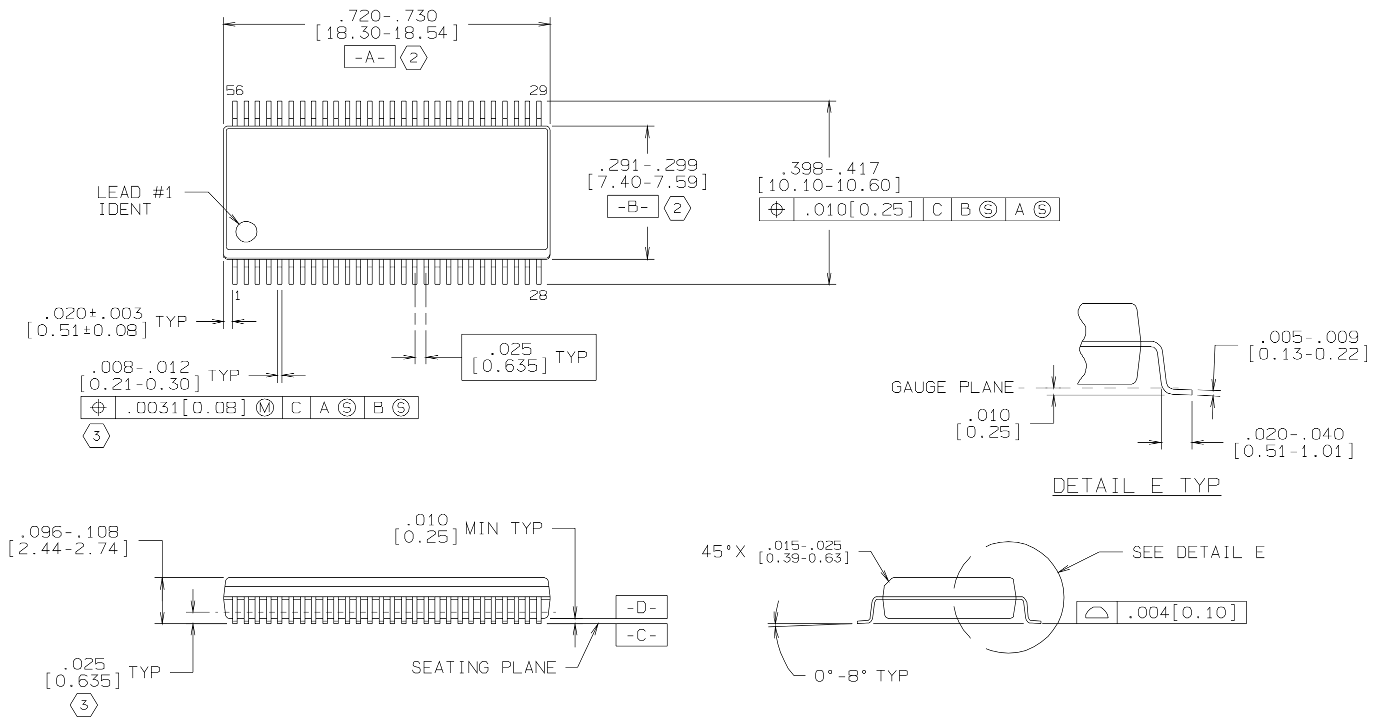
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	08421	03/28/91	KES/CC
B	POSITION TOL .007[0.18] WAS .010[0.25]; ADD NOTE 4.	10178	03/30/94	DEG/CC
C	TRUE POS:.0063[0.16] WAS .007[0.18]; LD PITCH:[0.635] WAS [0.63]; STANDOFF:.010[0.25] MIN WAS .008-.016 [0.21-0.40]; LD TIP TO LD TIP:.398-.417[10.11-10.59) WAS .395-.420[10.04-10.66].	10494	07/19/94	MS/DM
D	⌖ .0031[0.08] Ⓜ C A Ⓢ B Ⓢ WAS ⌖ .0063[0.160] Ⓜ D A Ⓢ B Ⓢ	10605	09/26/94	MS/KHT
E	TOP VIEW: ADD DIM .020±.003[0.51±0.08]; CHANGE DWG SIZE FROM B TO C.	11230	11/01/95	MS/



CONTROLLING DIMENSION IS INCH
VALUES IN [ ] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. STANDARD LEAD FINISH:
   200 MICROINCHES/5.08 MICROMETERS MINIMUM LEAD/TIN
   (SOLDER) ON COPPER.

⟨2⟩ DIMENSION DOES NOT INCLUDE MOLD FLASH.

⟨3⟩ MAXIMUM LEAD WIDTH ABOVE AREA SPECIFIED .018[0.45].

4. REFERENCE JEDEC REGISTRATION MO-118, VARIATION AB, DATED JUNE 1993.

APPROVALS	DATE
DRAWN Kurt Sincerbox	03/28/91
DFTG. CHK.	
ENGR. CHK.	

PROJECTION
INCH
[MM]

National Semiconductor
2900 Semiconductor dr, Santa Clara, CA 95052-8090

MOLDED PACKAGE,
SSOP, .300 WIDE,
56 LEAD

SCALE	SIZE	DRAWING NUMBER	REV
N/A	C	MKT-MS56A	E

DO NOT SCALE DRAWING | SHEET 1 OF 1